

IN THE CLAIMS

Please amend the claims to read as follows:

Listing of Claims

1. (Currently Amended) A semiconductor device layout inspection method for inspecting formation defects that will occur in wires of a chip layout, wherein the wire formation defects are detected by checking the relationship ratio between the layout of the contact holes in said wires and the layout of said wires.

2. (Original) The semiconductor device layout inspection method according to claim 1, wherein the layout of wires where wire formation defects have been detected is corrected.

3-17. (Canceled).